



PK658(v1.1) March 12, 2024

100% Material Declaration Data Sheet for Artix 7 FFG1156

Average Weight : 9.3634 g

Component	Substance Description	CAS # or Description	% of component	Use in product	Component weight / substance weight (in grams)	Component % of total
Silicon die	Silicon	7440-21-3	100.00	basis	0.237468	2.536%
					0.095245	1.017%
Bump	Tin	7440-31-5	98.20	basis	0.093531	
	Silver	7440-22-4	1.80	basis	0.001714	
					0.039500	0.422%
Underfill	Bisphenol F type liquid epoxy resin	9003-36-5	15.00	basis	0.005925	
	1,6-Bis(2,3-epoxypropoxy)naphthalene	27610-48-6	10.00	basis	0.003950	
	Bisphenol A type liquid epoxy resin	25068-38-6	5.00	basis	0.001975	
	Amine type hardener	trade secret	10.00	basis	0.003950	
	Silicon dioxide	60676-86-0	58.00	filler	0.022910	
	Carbon black	1333-86-4	1.00	color agent	0.000395	
	Additives	trade secret	1.00	additives	0.000395	
					4.965400	53.030%
Heat sink	Copper	7440-50-8	98.35	Main material	4.883471	
	Nickel	7440-02-0	1.65	Main material	0.081929	
					0.097500	1.041%
Heat sink adhesive	Aluminium Oxide Al2O3	1344-28-1	70.00	Main material	0.068250	
	Dimethyl siloxane, dimethylvinyl-terminated	68083-19-2	30.00	Main material	0.029250	
					0.965683	10.31%
Solder ball	Tin	7440-31-5	96.50	Main material	0.931884	
	Silver	7440-22-4	3.00	Main material	0.028970	
	Copper	7440-50-8	0.50	Main material	0.004828	
					2.962620	31.640%
Substrate	Copper	7440-50-8	26.64	Metallization	0.789167	
	Gold	7440-57-5	0.01	Metallization	0.000337	
	Palladium	7440-50-3	0.00	Metallization	0.000139	
	Nickel	7440-02-0	0.53	Metallization	0.015795	
	Tin	7440-31-5	0.17	Metallization	0.005155	
	Silver	7440-22-4	0.01	Metallization	0.000160	
	Core	Trade Secret	55.66	Core	1.649051	
	ABF	Trade Secret	14.62	Build Up	0.433062	
	Solder Mask	Trade Secret	2.04	Solder Mask	0.060445	
	Resine Plugging	Trade Secret	0.31	Resine Plugging	0.009310	

Revision History

Date	Version	Description of Revisions
5/23/2014	1.0	Initial AMD Release.
5/23/2014	1.1	Changed per XCN23002

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